



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-09-26
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPSC1006D	HSDK*DC051Y4	A	SHENZHEN B/E	2016-09-26
	Amount	UoM	Unit type	ST ECOPACK Grade
	1860.00	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-16.25-4.5	2	THROUGH HOLE	
Comment	DO 220			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HSDK*DC051Y4					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.062	mg	supplier	die	Silicium carbide	409-21-2		0.032	mg	30132	17
				supplier	metallization	Aluminium (Al)	7429-90-5		0.985	mg	927495	530
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	942	1
				supplier	back side metallization	Gold (Au)	7440-57-5		0.003	mg	2825	2
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.016	mg	15066	9
				supplier	polymer die coating	Probimide	proprietary		0.025	mg	23540	13
Leadframe	Copper & its alloys	1185.417	mg	supplier	alloy	Copper (Cu)	7440-50-8		1182.771	mg	997768	635898
				supplier	alloy	Iron (Fe)	7439-89-6		1.184	mg	999	637
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.355	mg	299	191
				supplier	metallization	Nickel (Ni)	7440-02-0		1.107	mg	934	595
Soft solder	Solder	2.524	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	2.411	mg	955230	1294
				supplier	solder	Silver (Ag)	7440-22-4		0.063	mg	24960	34
				supplier	solder	Tin (Sn)	7440-31-5		0.050	mg	19810	27
Bonding wires	Other inorganic materials	1.385	mg	supplier	wire	Aluminium (Al)	7429-90-5		1.385	mg	1000000	745
Encapsulation	Other Organic Materials	665.371	mg	supplier	mold compound	Silica, vitreous	60676-86-0		578.873	mg	870000	311222
				supplier	mold compound	Epoxy resin	25068-38-6		66.537	mg	100000	35773
				supplier	mold compound	Phenol resin	29690-82-2		16.634	mg	25000	8943
				supplier	mold compound	Carbon Black	1333-86-4		3.327	mg	5000	1789
Connections coating	Solder	4.241	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		4.241	mg	1000000	2280